

L Number	Hits	Search Text	DB	Time stamp
1	47	(US-5644586-\$ or US-4807022-\$ or US-4631573-\$ or US-4791634-\$ or US-3764935-\$ or US-5918665-\$ or US-5898211-\$ or US-5864176-\$ or US-3614550-\$ or US-4712609-\$ or US-5801442-\$ or US-6347050-\$ or US-6274912-\$ or US-5206871-\$ or US-4766585-\$ or US-3806830-\$ or US-6198758-\$ or US-6172997-\$ or US-6157077-\$ or US-5812570-\$ or US-5783862-\$ or US-5729052-\$ or US-5241450-\$ or US-3654528-\$ or US-3943426-\$ or US-6144683-\$).did. or (US-6252250-\$ or US-5785754-\$ or US-6310900-\$ or US-6307871-\$ or US-6272159-\$).did. or (US-20010004312-\$ or US-20010004370-\$).did. or (DE-3436545-\$ or DE-3638102-\$ or DE-4208891-\$).did. or (JP-08227953-\$ or JP-09102568-\$ or JP-02257683-\$ or JP-63073584-\$ or JP-08181392-\$ or JP-08139479-\$).did. or (DE-4322933-\$ or DE-4208891-\$ or JP-09102568-\$ or EP-715352-\$ or JP-08139479-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/11 14:12
2	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/11 14:20
3	9335	((257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.	USPAT; US-PGPUB	2004/01/11 15:29
4	0	((257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.) and heat adj sink and (fluid liquid water) near12 (inject injecting injection) and supply near12 rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:23
5	5	heat adj sink and (fluid liquid water) near12 (inject injecting injection) and supply near12 rubber and laser	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:27
6	2	jp-08227953\$-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:28
7	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:29
8	0	09102568\$-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:29
9	2	jp-09102568\$-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:32

10	2	jp-09102568\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:33
11	2	jp-08139479\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:36
12	367	(361/689).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:39
13	19	((361/689).CCLS.) and heat adj sink and rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:39
14	0	((361/689).CCLS.) and heat adj sink and rubber near12 supply	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:39
15	303	(361/702).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:39
16	1	((361/702).CCLS.) and heat adj sink and rubber near12 supply	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 14:40
17	10110	((257/706) or (257/707) or (257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.	USPAT; US-PGPUB	2004/01/11 15:32
18	775	((257/706) or (257/707) or (257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.) not (((257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 15:30
19	0	((257/706) or (257/707) or (257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.) not (((257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.)) and rubber near6 supply	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 15:30

20	11746	((257/678) or (257/701) or (257/706) or (257/707) or (257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.	USPAT; US-PGPUB	2004/01/11 15:32
21	2411	((257/678) or (257/701) or (257/706) or (257/707) or (257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.) not (((257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 15:33
22	0	((257/678) or (257/701) or (257/706) or (257/707) or (257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.) not (((257/712) or (257/713) or (257/714) or (257/715) or (361/689) or (361/702) or (372/34) or (372/35) or (372/36) or (372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50)).CCLS.) and rubber near12 supply	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 15:35
23	699	(257/707).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 16:34
24	1058	(257/706).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 16:34
25	794	((257/706).CCLS.) not ((257/707).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 16:34
26	33	((257/706).CCLS.) not ((257/707).CCLS.) and heat adj sink and rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 16:36
27	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 16:39
28	1267	(257/714).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 16:39
29	92	((257/714).CCLS.) and rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 16:44
30	324	(361/689).CCLS.	USPAT; US-PGPUB	2004/01/11 18:33

31	605	(361/699).CCLS.	USPAT; US-PGPUB	2004/01/11 16:51
32	91	((361/699).CCLS.) and rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:01
33	1791	((257/701) or (257/678)).CCLS.	USPAT; US-PGPUB	2004/01/11 17:01
34	114	((257/701) or (257/678)).CCLS.) and rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:01
35	0	((257/701) or (257/678)).CCLS.) and rubber near12 supply	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:01
36	295	((257/701) or (257/678)).CCLS.) and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:02
37	15	((257/701) or (257/678)).CCLS.) and heat adj sink near12 (water liquid fluid)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:03
38	1836	(257/678).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:03
39	1077	(257/701).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:03
40	1058	(257/706).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:03
41	699	(257/707).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:03
42	5008	((257/678).CCLS.) ((257/701).CCLS.) ((257/706).CCLS.) ((257/707).CCLS.) "L42"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:10
43	4240	((257/678).CCLS.) ((257/701).CCLS.) ((257/706).CCLS.) ((257/707).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:10
44	0	((257/678).CCLS.) ((257/701).CCLS.) ((257/706).CCLS.) ((257/707).CCLS.)) and rubber near12 supply	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:26
46	1	((257/717).CCLS.) and rubber near12 spacer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:27

45	925	(257/717).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:45
47	2	jp-09102568\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:47
48	2	de-3436545\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:48
49	0	jp-081811392\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:49
50	2	jp-08181392\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:50
51	2	("5794839").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:51
52	2	("4791634").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:54
53	1	gb-1597829\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 17:54
54	4146	((327/34) or (327/35) or (372/36) or (257/678) or (257/712) or (257/714) or (361/689) or (361/702)).CCLS.	USPAT; US-PGPUB	2004/01/11 18:34
55	5	((327/34) or (327/35) or (372/36) or (257/678) or (257/712) or (257/714) or (361/689) or (361/702)).CCLS.) and laser and rubber and heat adj sink and supply near12 (liquid fluid coolant water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 18:36
56	0	((327/34) or (327/35) or (372/36) or (257/678) or (257/712) or (257/714) or (361/689) or (361/702)).CCLS.) and laser and insulat\$3 near6 rubber and heat adj sink and supply near12 (liquid fluid coolant water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/01/11 18:36
-	2	jp-09102568\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/12/08 14:30
-	2	jp-08227953\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 16:22
-	2	jp-08139479\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 16:24

-	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/06 16:24
-	2008	((372/34) or (372/35) or (372/36)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:24
-	996	heat adj sink.ti. and 257/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 07:45
-	33	heat adj sink.ti. and liquid.ti,ab. and 257/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:28
-	20	((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and laser.ti,ab. and heat adj sink.ti,ab. and (liquid or water).ti,ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/07 08:27
-	8	(US-6307871-\$ or US-5801442-\$ or US-4791634-\$ or US-4712609-\$ or US-3764935-\$).did. or (US-20010004370-\$).did. or (JP-02257683-\$ or JP-63073584-\$).did.	USPAT; US-PGPUB; JPO	2002/08/07 08:49
-	388	(257/365).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/08 15:44
-	6068	((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:50
-	307	((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:52
-	110	((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:53
-	63	(((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 12:55
-	40	(((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))) and semiconductor	USPAT	2002/08/09 12:56

-	44	(((((372/34) or (372/35) or (372/36)).CCLS.) or ((257/712) or (257/713) or (257/714) or (257/715)).CCLS.)) and heat adj sink and (liquid or water) near6 (cooler or coolant)) and (groove or slit or trench)) and (stack or (upper near12 lower))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/09 13:32
-	1	heat adj sink.ti. and liquid.ti,ab. and 372/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:29
-	33	heat adj sink.ti. and 372/\$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 15:29
-	10026	heat adj sink and upper near12 lower	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:24
-	710	heat adj sink.ti. and upper near12 lower	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:25
-	70	heat adj sink.ti. and upper near12 lower near12 (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:26
-	30	heat adj sink.ti. and upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:31
-	2	heat adj sink.ti. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:33
-	2	heat adj sink.ti,ab. and (groove or trench) near12 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:34
-	2	heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower adj (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:35
-	4	heat adj sink.ti,ab. and (groove or trench) near18 upper near6 lower near6 (face or main adj surface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:52
-	6	heat adj sink.ti,ab. and (groove or trench) near18 ((upper near18 lower) near18 (face or main adj surface))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 11:54
-	4163	((257/712) or (257/713) or (257/714) or (257/715)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 14:08

-	1156	(372/34).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:25
-	423	(372/35).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:25
-	661	(372/36).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	1884	(257/712).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	958	(257/713).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	1193	(257/714).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	493	(257/715).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:26
-	6144	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:27
-	4269	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.) and (heat adj removal or heat adj sink or coolant or cooling)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:28
-	3590	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.) and (heat adj removal or heat adj sink or coolant or cooling).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:29
-	1280	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.) and (heat adj removal or heat adj sink or coolant or cooling).ti,ab,clm. and liquid	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:29
-	263	((372/34).CCLS.) or ((372/35).CCLS.) or ((372/36).CCLS.) or ((257/712).CCLS.) or ((257/713).CCLS.) or ((257/714).CCLS.) or ((257/715).CCLS.) and (heat adj removal or heat adj sink or coolant or cooling).ti,ab,clm. and liquid and (groove or trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 15:30

-	27	(US-6198758-\$ or US-6310900-\$ or US-3654528-\$ or US-4807022-\$ or US-5729052-\$ or US-5783862-\$ or US-5864176-\$ or US-5918665-\$ or US-6157077-\$ or US-6274912-\$ or US-6347050-\$ or US-5801442-\$ or US-4712609-\$ or US-3764935-\$ or US-5241450-\$ or US-4791634-\$ or US-5812570-\$ or US-6307871-\$).did. or (US-20010004370-\$).did. or (JP-02257683-\$ or JP-63073584-\$ or JP-09102568-\$ or JP-08227953-\$ or JP-08139479-\$).did. or (JP-09102568-\$ or EP-715352-\$ or JP-08139479-\$).did.	USPAT; US-PGPUB; JPO; DERWENT	2002/08/23 18:39
-	5	((US-6198758-\$ or US-6310900-\$ or US-3654528-\$ or US-4807022-\$ or US-5729052-\$ or US-5783862-\$ or US-5864176-\$ or US-5918665-\$ or US-6157077-\$ or US-6274912-\$ or US-6347050-\$ or US-5801442-\$ or US-4712609-\$ or US-3764935-\$ or US-5241450-\$ or US-4791634-\$ or US-5812570-\$ or US-6307871-\$).did. or (US-20010004370-\$).did. or (JP-02257683-\$ or JP-63073584-\$ or JP-09102568-\$ or JP-08227953-\$ or JP-08139479-\$).did. or (JP-09102568-\$ or EP-715352-\$ or JP-08139479-\$).did.) and laser adj diode ("4791634").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/23 18:39
-	2	jp-8227953\$-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 14:12
-	0	jp-8227953\$-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 14:13
-	2	jp-08227953\$-\$).did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 14:13
-	21	zengerle.in. and heat	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 15:25
-	4	zengerle.in. and power adj semiconductor adj component	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/24 15:26
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 14:06
-	127	((((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:18

-	103	((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow)	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:24
-	103	((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and heat adj sink.ti,ab,clm.	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:24
-	4	((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and (groove or slit) near12 heat adj sink	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:32
-	5	((372/43) or (372/44) or (372/45) or (372/46) or (372/47) or (372/48) or (372/49) or (372/50) or (372/34) or (372/35) or (372/36) or (257/712) or (257/713) or (257/714) or (257/715)).CCLS.) and heat adj sink.ti,ab,clm. and semiconductor adj laser and (coolant or water or fluid or flow) and (groove or slit) near12 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:48
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/10 15:49
-	1627	(257/678).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:15
-	36	((257/678).CCLS.) and heat adj sink.ti,ab,clm. and (liquid or water or flow or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:39
-	109	hayashi.in. and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:40
-	18	hayashi.in. and laser.ti,ab,clm. and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:42
-	2	jp-09102568\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 13:54

-	1442	heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 13:56
-	3	lsi and (heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 13:59
-	2	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:00
-	4	(heat adj sink.ti,ab,clm. and semiconductor adj laser.ti,ab,clm.) and liquid adj coolant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:09
-	491	semiconductor adj laser near6 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:09
-	249	semiconductor adj laser near3 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:11
-	1	(semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and liquid adj coolant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:12
-	35	(semiconductor adj laser near3 heat adj sink.ti,ab,clm.) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 15:03
-	2	jp-08227953\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 14:14
-	2	("3351698").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 15:22
-	0	("heat adj sink near20 laser near20 electrode near20 copper").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 15:22
-	19	heat adj sink near20 laser near20 electrode near20 copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 15:53
-	0	top adj electrode near12 bottom adj electrode near20 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 15:55
-	44	"electrodes" near12 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 15:56

-	29	"electrodes" near6 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 15:56
-	8	"electrodes" near3 copper and semiconductor.ti,ab,clm. and laser.ti,ab,clm. and heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:02
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:02
-	2118	heat adj sink near12 electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:07
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:18
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:34
-	2	guiding adj (hole or through-hole or aperture) near12 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:51
-	115	(hole or through-hole or aperture) near12 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:53
-	103	(hole or through-hole or aperture) near6 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:55
-	57	(hole or through-hole or aperture) near3 (guide or guiding) and heat adj sink.ti,ab,clm. and (liquid or water or coolant)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:56
-	3	(hole or through-hole or aperture) near3 (guide or guiding) near12 heat adj sink near12 (liquid or water or coolant) and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 19:59
-	2	jp-09102568\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:00
-	2	jp-08227953\$-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:01
-	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/12 20:30

-	0	("heat adj sink near12 (leak or leakage or leaking) near12 rubber").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 20:30
-	0	heat adj sink near12 (leak or leakage or leaking) near12 rubber	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 20:31
-	0	heat adj sink near12 (leak or leakage or leaking) near12 (elastic rubber)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 20:32
-	20	heat adj sink near12 (leak or leakage or leaking) near12 (elastic rubber insulating insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 21:09
-	2	jp-08181392\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/12 21:09
-	87	stack near4 heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 09:31
-	6	(stack near4 heat adj sink.ti,ab,clm.) and (rubber or elastic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 10:14
-	5	(stack near4 heat adj sink.ti,ab,clm.) and (rubber or elastic or spacer) near12 (insulat\$3 or isolat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 10:15
-	29	riser near6 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 11:04
-	2	riser near10 heat adj sink near10 (liquid or flow or fluid or coolant or water)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 11:05
-	28	riser near10 (liquid or flow or fluid or coolant or water) and heat adj sink.ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 11:53
-	2	("5794839").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 13:19
-	7	semiconductor adj laser.ti,ab,clm. and heat adj sink.ti,ab,clm. and (stack or stacked) near3 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 14:10
-	1	heat adj sink.ti,ab,clm. and (stack or stacked) near3 heat adj sink and (upper adj electrode near20 lower adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/13 14:08

-	2	semiconductor.ti,ab,clm. and heat adj sink.ti,ab,clm. and (stack or stacked) adj heat adj "sinks" and (top upper) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:22
-	36	(((((slug or spreader or dissipat\$3) near12 (heat thermal)) and semiconductor.ti,ab,clm.) and (coolant flow liquid water)) and (stack stacked) near2 ("heat sinks"))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 14:28
-	9	(((((slug or spreader or dissipat\$3) near12 (heat thermal)) and semiconductor.ti,ab,clm.) and (coolant flow liquid water)) and (stack stacked) near2 ("heat sinks")) and (riser or guid\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 15:21
-	174	257/625	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:09
-	8124	((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:23
-	1	((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (riser guide guiding) near12 (flow liquid water coolant) and (stack stacked) near2 heat adj sink	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:13
-	2	((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and stacked adj heat adj sinks	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:39
-	10	((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:45
-	0	((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks) and (first upper top) adj electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:46
-	2	((((257/625) or (257/675) or (257/717) or (257/720) or (257/712) or (257/713) or (257/714) or (257/715) or (372/34) or (372/35) or (372/36)).CCLS.) and (stack stacked stacking) near2 heat adj sinks) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:49
-	0	stacked adj heat adj sinks.ti,ab,clm. and semiconductor adj2 (element device) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 16:51
-	4	(stack stacking stacked) near12 heat adj sinks and semiconductor adj2 (element device) and ((top upper) adj electrode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:31
-	2	("4631573").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 17:31

-	3	("5785754").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 17:31
-	1	stacked.ti,ab,clm. and heat adj sink.ti,ab,clm. and (electronic or semiconductor) adj (device or element) and "in series"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:34
-	0	semiconductor adj laser.ti,ab,clm. and (372/4\$1.ccls. or 372/50.ccls.) and stacked and "in series"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:35
-	74	semiconductor adj laser.ti,ab,clm. and (372/4\$1.ccls. or 372/50.ccls.) and stacked and series	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:53
-	8	stacked near3 active near3 region near3 monolithic near3 laser near3 array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:55
-	2	("5157680").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 19:55
-	20	stacked near12 active near12 laser near12 array	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 20:35
-	2	("4791634").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:07
-	2	("6144683").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:08
-	0	("jp-8181392\$-\$\$.did.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:09
-	2	jp-08181392\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:09
-	0	bell.in. and morrison.in. and law.in. and malcolm.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:11
-	1	gb-1597829\$-\$\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:12
-	2	("6144683").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/13 21:23

-	1	("0773510").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 08:47
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 08:48
-	5	773509.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/05/14 08:48
-	4	773510.ap.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/12/08 14:07